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ELECTRONIC COMPONENTS  
AND PACKAGING

## Data Sheet: 95 Lead-5 Indium

### Physical Properties of Bulk Solder

Solder Alloy Composition	95Pb-5In (weight per cent)
Melting range	302-314°C
Density	11.04 Mg/m <sup>3</sup>
Thermal conductivity	0.21 W/cm K <sup>-1</sup>
Electrical conductivity	5.1% IACS
Coefficient of Thermal Expansion	29.0 x 10 <sup>-6</sup> K <sup>-1</sup>
Tensile strength (est.)	29.8 GNm <sup>-2</sup>
Shear strength	22.2 GNm <sup>-2</sup>

Typical impurity levels for electronic grade are less than:

Au: 0.05	Ag : 0.05	Cu: 0.08	Ni: 0.01	Al: 0.0005
Bi: 0.001	Fe: 0.02	Zn: 0.0003	As: 0.0003	Cd: 0.002
Sn: 0.10				

The 95Pb5in-alloy is used for the manufacture of semiconductor components. It combines a higher melting range, with good mechanical strength and thermal fatigue properties. The 5% indium assures wetting to copper leads and Au-flash coated Si-chips in die-attach applications. The melting temperature range is wide enough to permit two-or even three-step soldering. The higher melting range makes the alloy also very suitable for fluxless soldering in an inert or reducing atmosphere.

The 5% In solder requires careful packaging as it forms a rather tenacious surface oxide, requiring a longer and higher temperature profile than the Sn-based high lead solders. The alloy is used in the assembly of diodes and rectifiers in belt furnaces with a forming gas mixture (N<sub>2</sub>, H<sub>2</sub>) or cracked anhydrous ammonia (75%H<sub>2</sub>, 25%N<sub>2</sub>).

**Application:** Soldering temperature profile for flux-less, reflow applications should include: minimal at or above 360°C for a minimal time of 120 seconds. This assumes clean, soldering surfaces and the presence of a reducing- or inert-atmosphere during the soldering cycle. Alternatively, the alloy can be reflowed below 360°C when special conditions for substrates (i.e. Au-plating over Ni-) and longer temperatures above melting point are being met.

If and when the components are slightly oxidized, a combination of higher temperatures and/or longer soldering temperatures is required.

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